TWENTY THIRD ANNUAL

May 1 - 4, 2022

TestConX

DoubleTree by Hilton Mesa, Arizona ACCINE

© 2022 TestConX– Image: f11-photographer / iStock





High Frequency & High Current

Stamped Spring Probe

Samuel Pak & A J Park IWIN Co., Ltd.

Introduction

Testing environment requires advanced technologies to support ever increasing demands. Test industry and test socket for semiconductor process have one of the most challenging interconnect applications in electronics due to the combination of harsh operating conditions and extremely high performance requirements, 80 GHz and beyond. With high current carrying for high frequency.

Various kinds of High Frequency Test socket



with Stamped Spring Probe

Big scale/ High pin count For a large-sized package, pins with a length enabling high speed test also available.

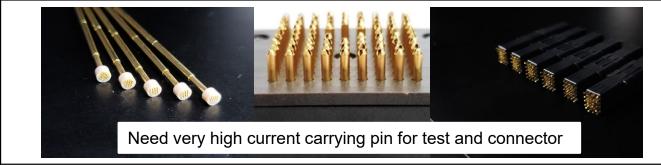


Small scale/ Low pin count can be tested extremely high frequency with very

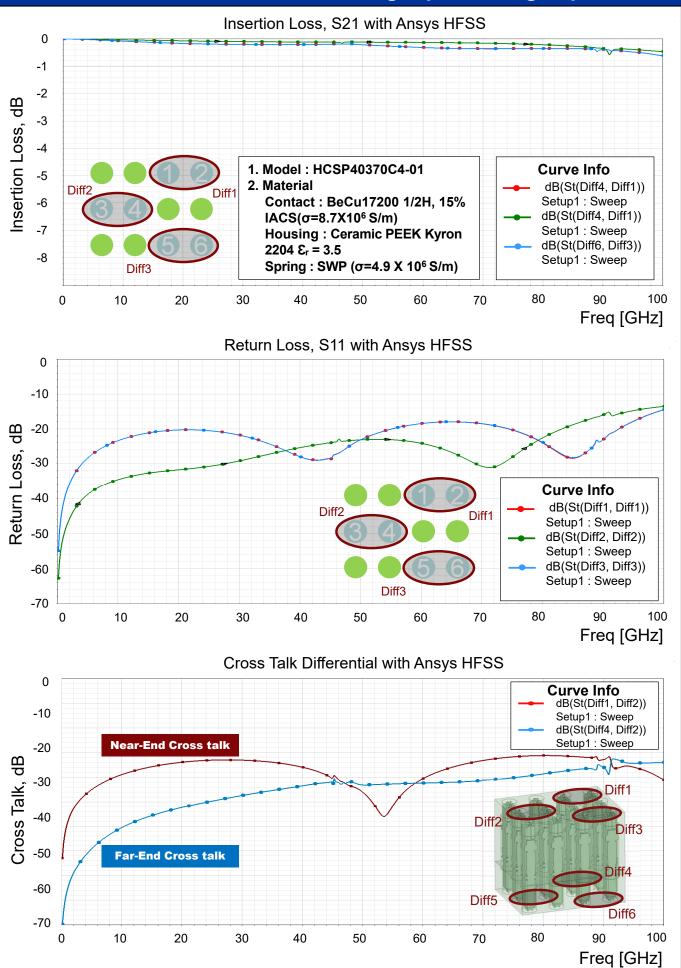
Pictures of Test sockets for high speed test

Various kinds of High Current Stamped Spring Probe

short length pin.

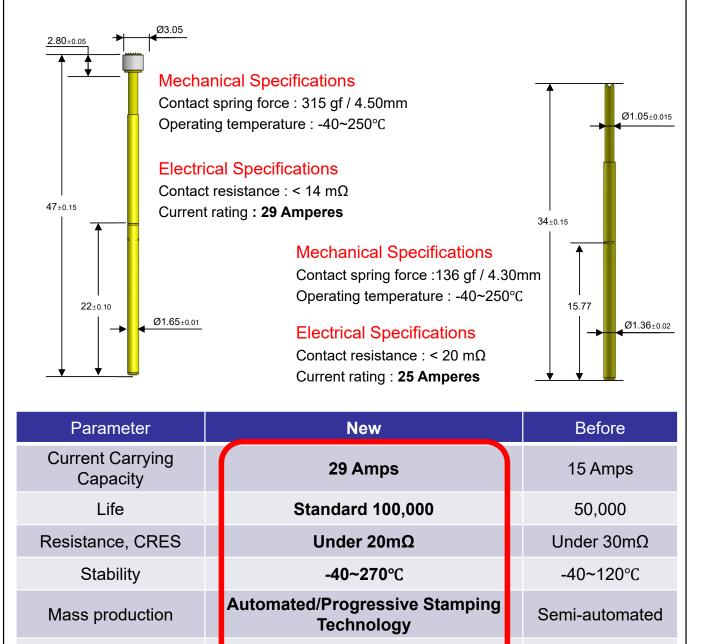


HCSP61452C4-01 // 4.52mm length pin but high speed



TestConX 2022

Various kinds of High Current Stamped Spring Probe



Quality Control

Summaries and the next plan

Automated

- Selection of high performance spring probe pin is critical
- Incredibly high speed parts/minute production by stamping
- 0.67mm test height pin is already under mass production the pins demonstrated high performance and long life.
- Pin for a big scale/high pin count socket is ready
- Improved with high current carrying using stamping technology
- Relatively easier quality management once stamping tool is qualified.
- Reduce lead time for stamping tool for a new pin development

Semi-Automated

With Thanks to Our Sponsors!





With Thanks to Our Sponsors!





COPYRIGHT NOTICE

The presentation(s) / poster(s) in this publication comprise the Proceedings of the TestConX 2022 workshop. The content reflects the opinion of the authors and their respective companies. They are reproduced here as they were presented at the TestConX 2022 workshop. This version of the presentation or poster may differ from the version that was distributed at or prior to the TestConX 2022 workshop.

The inclusion of the presentations/posters in this publication does not constitute an endorsement by TestConX or the workshop's sponsors. There is NO copyright protection claimed on the presentation/poster content by TestConX. However, each presentation / poster is the work of the authors and their respective companies: as such, it is strongly encouraged that any use reflect proper acknowledgement to the appropriate source. Any questions regarding the use of any materials presented should be directed to the author(s) or their companies.

"TestConX", the TestConX logo, and the TestConX China logo are trademarks of TestConX. All rights reserved.

www.testconx.org